

STGF7NB60SL N-CHANNEL 7A - 600V - TO-220FP PowerMESH™ IGBT

Table 1: General Features

ТҮРЕ	V _{CES}	V _{CE(sat)} (Max) @25°C	lc @100°C
STGF7NB60SL	600 V	< 1.6 V	7 A

- POLYSILICON GATE VOLTAGE DRIVEN
- LOW THRESHOLD VOLTAGE
- LOW ON-VOLTAGE DROP
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY

DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH[™] IGBTs, with outstanding performances. The suffix "S" identifies a family optimized achieve minimum on-voltage drop for low frequency applications (<1kHz).

APPLICATIONS

- LIGHT DIMMER
- STATIC RELAYS

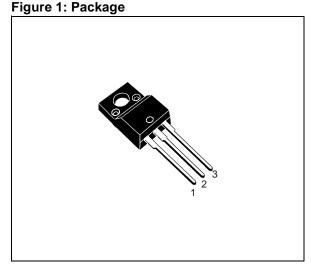


Figure 2: Internal Schematic Diagram

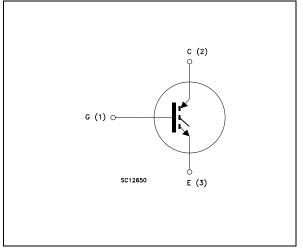


Table 2: Order Codes

SALES TYPE	MARKING	PACKAGE	PACKAGING
STGF7NB60SL	GF7NB60SL	TO-220FP	TUBE

Symbol	Parameter	Value	Symbol
V _{CES}	Collector-Emitter Voltage (V _{GS} = 0)	600	V
V _{ECR}	Reverse Battery Protection	20	V
V _{GE}	Gate-Emitter Voltage	± 20	V
Ι _C	Collector Current (continuous) at 25°C	15	A
Ι _C	Collector Current (continuous) at 100°C	7	A
I _{СМ} (1)	Collector Current (pulsed)	20	A
Ртот	Total Dissipation at $T_C = 25^{\circ}C$	25	W
	Derating Factor	0.2	W/°C
VISO	Insulation Withstand Voltage A.C.	2500	V
T _{stg}	Storage Temperature - 55 to 150		°C
Tj	Operating Junction Temperature	- 55 10 150	

Table 3: Absolute Maximum ratings

(1)Pulse width limited by max. junction temperature.

Table 4: Thermal Data

Rthj-case	Thermal Resistance Junction-case Max	5	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_{CASE} =25°C UNLESS OTHERWISE SPECIFIED) Table 5: Off

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{BR(CES)}	Collectro-Emitter Breakdown Voltage	I _C = 250 μA, V _{GE} = 0	600			V
V _{BR(ECS)}	Emitter-Collector Breakdown Voltage	$I_{C} = 1$ mA, $V_{GE} = 0$	20			V
I _{CES}	Collector-Emitter Leakage Current (V _{CE} = 0)	V _{GE} = Max Rating Tc=25°C Tc=125°C			10 100	μΑ μΑ
I _{GES}	Gate-Emitter Leakage Current (V _{CE} = 0)	$V_{GE} = \pm 20 \text{ V}$, $V_{CE} = 0$			±100	nA

Table 6: On

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GE(th)}	Gate Threshold Voltage	$V_{CE}=V_{GE}, I_{C}=250 \ \mu A$	1.2		2.4	V
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	V _{GE} =4.5 V, I _C = 7A, Tj= 25°C V _{GE} =4.5 V, I _C = 7A, Tj= 125°C		1.2 1.1	1.6	V V

ELECTRICAL CHARACTERISTICS (CONTINUED)

Table 7: Dynamic

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g fs	Forward Transconductance	$V_{CE} = 15 V, I_{C} = 7 A$		5		S
C _{ies} C _{oes} C _{res}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{CE} = 25V, f = 1 MHz, V _{GE} = 0		800 60 10		pF pF pF
Q _g Q _{ge} Q _{gc}	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	$V_{CE} = 480V$, $I_C = 7 A$, $V_{GE} = 5V$ (see Figure 20)		16 2.5 8.5	22	nC nC nC
I _{CL}	Turn-Off SOA Minimum Current	$V_{clamp} = 480 \text{ V}$, Tj = 125°C R _G = 1 K Ω , V _{GE} =5V	20			A
tscw	Short Circuit Withstand Time	$\label{eq:Vce} \begin{array}{l} V_{ce} = 0.5 \; V_{BR(CES)}, \; V_{GE} {=} 5V, \\ Tj = 125^\circC \; , \; R_G = 1K\Omega \end{array}$		14		μs

Table 8: Switching On

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Current Rise Time	$\label{eq:VCC} \begin{array}{l} V_{CC} = 480 \text{ V}, \text{ I}_{C} = 7 \text{ A R}_{G} \text{=} 1 \text{K} \Omega \text{ ,} \\ \text{ V}_{GE} = 5 \text{ V} \\ \text{(see Figure 18)} \end{array}$		1.1 0.25		µs µs
(di/dt) _{on} E _{on}	Turn-on Current Slope Turn-on Switching Losses	$\label{eq:VCC} \begin{array}{l} V_{\text{CC}} = 480 \ \text{V}, \ I_{\text{C}} = 7 \ \text{A} \ R_{\text{G}} {=} 1 \text{K} \Omega \\ V_{\text{GE}} = 5 \ \text{V}, Tj = 125^{\circ} \text{C} \end{array}$		45 2.7		A/µs mJ

Table 9: Switching Off

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _c	Cross-over Time	$V_{cc} = 480 \text{ V}, \text{ I}_{C} = 7 \text{ A},$		2.7		μs
$t_r(V_{off})$	Off Voltage Rise Time	$R_{GE} = 1K\Omega$, $V_{GE} = 5 V$ (see Figure 18)		1.6		μs
t _d (_{off})	Delay Time			5.2		μs
t _f	Current Fall Time			1.1		μs
E _{off} (**)	Turn-off Switching Loss			4.1		mJ
t _c	Cross-over Time	$V_{cc} = 480 \text{ V}, \text{ I}_{C} = 7 \text{ A},$		4.4		μs
$t_r(V_{off})$	Off Voltage Rise Time	R _{GE} = 1KΩ , V _{GE} = 5 V Tj = 125 °C		2.4		μs
t _d (_{off})	Delay Time	(see Figure 18)		6.4		μs
t _f	Fall Time			1.7		μs
E _{off} (**)	Turn-off Switching Loss			7.1		mJ

(**)Turn-off losses include also the tail of the collector current.

Figure 3: Output Characteristics

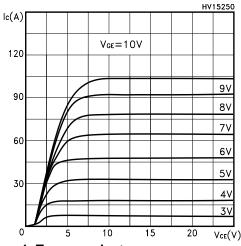


Figure 4: Transconductance

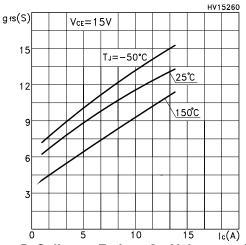


Figure 5: Collector-Emitter On Voltage vs Collector Current

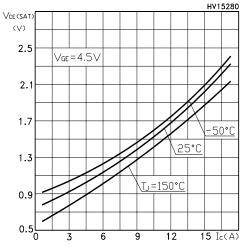


Figure 6: Transfer Characteristics

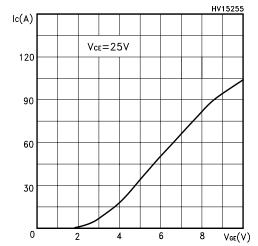
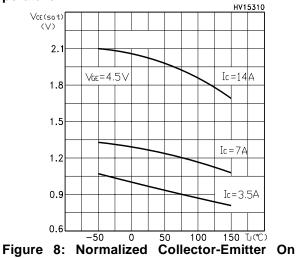
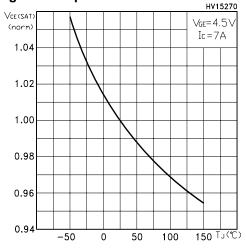


Figure 7: Collector-Emitter On Voltage vs Temperature



Voltage vs Temperature



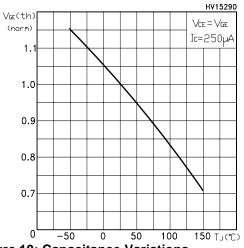


Figure 9: Gate Thereshold vs Temperature

Figure 10: Capacitance Variations

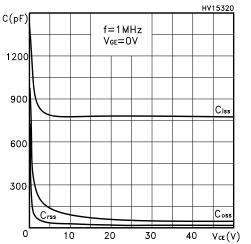


Figure 11: Total Switching Losses vs Gate Resistance

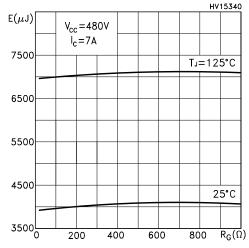


Figure 12: Normalized Breakdown Voltage vs Temperature

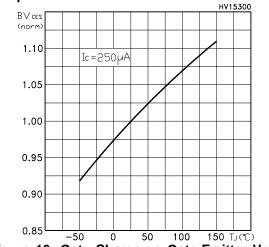


Figure 13: Gate Charge vs Gate-Emitter Voltage

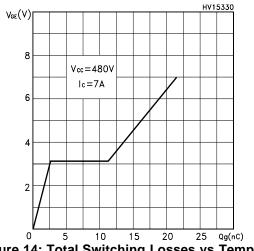
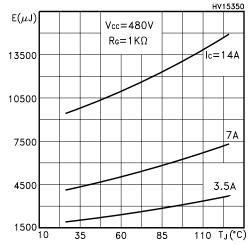


Figure 14: Total Switching Losses vs Temperature



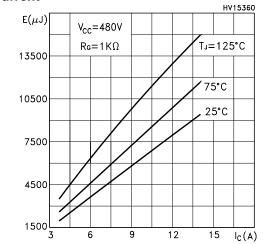


Figure 15: Total Switching Losses vs Collector Current

Figure 16: Thermal Impedance

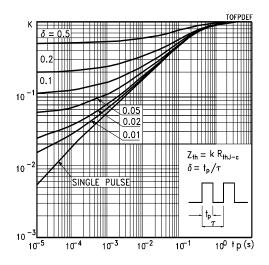
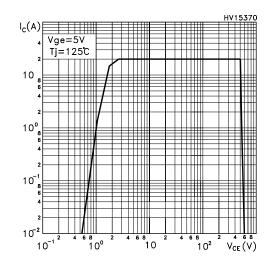


Figure 17: Turn-Off SOA



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Figure 18: Test Circuit for Inductive Load Switching

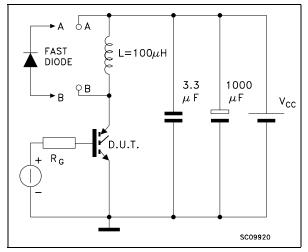


Figure 19: Switching Waveforms

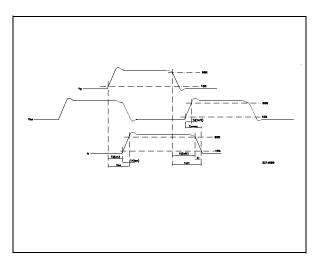


Figure 20: Gate Charge Test Circuit

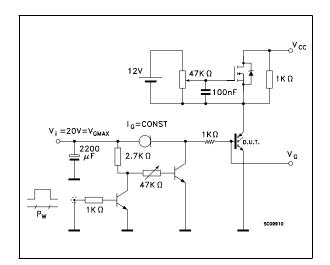


Table 10: Revision History

Date	Revision	Description of Changes
04-June-2004	2	Stylesheet update. No content change
02-Sep-2004	3	Datasheet updated, see table1

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